

Part Number: L-36BID

High Efficiency Red

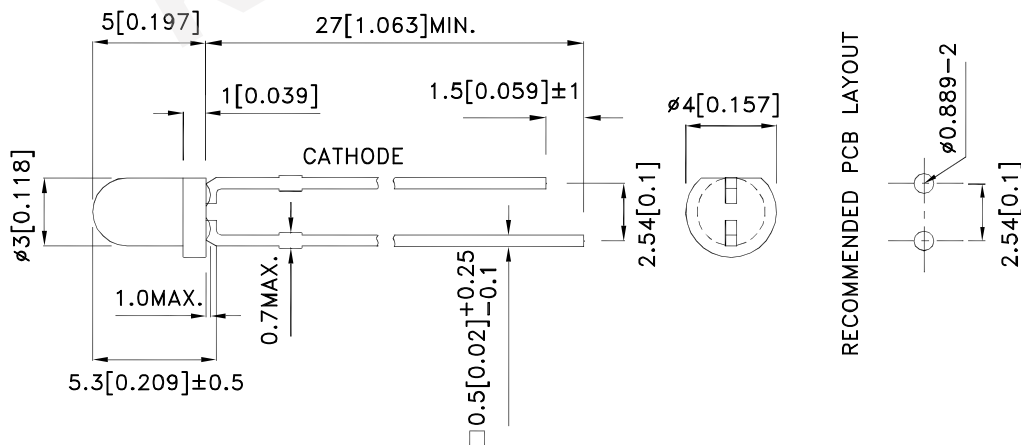
Features

- T-1 package with rectangular base.
- With built-in blinking IC.
- Operation voltage from 3.5V to 14V.
- Blinking frequency from 3.0Hz to 1.5Hz.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) V= 9V		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-36BID	High Efficiency Red (GaAsP/GaP)	Red Diffused	12	25	60°
			*6	*15	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Min.	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red		627		nm	
λD	Dominant Wavelength	High Efficiency Red		617		nm	
Δλ1/2	Spectral Line Half-width	High Efficiency Red		45		nm	
IF	Forward Current	High Efficiency Red	8	22		mA	Min:VF=3.5V Typ:VF=5V
ISON	Supply Current	High Efficiency Red		8		mA	VF=3.5V
ISON	Supply Current	High Efficiency Red		44		mA	VF=14V
f	Blink Frequency	High Efficiency Red	1.5		3	Hz	VF=3.5V~14V

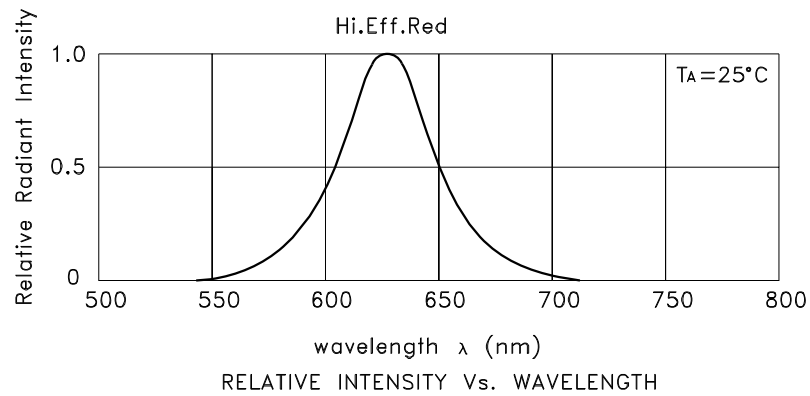
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units
Power dissipation	310	mW
Forward Voltage	14	V
Reverse Voltage	0.5	V
Operating Temperature	-40°C To +70°C	
Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [1]	260°C For 3 Seconds	
Lead Solder Temperature [2]	260°C For 5 Seconds	

Notes:

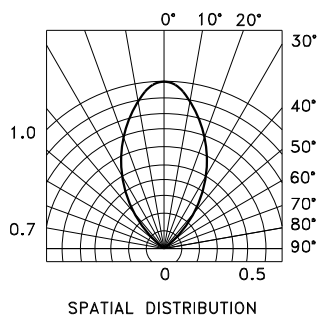
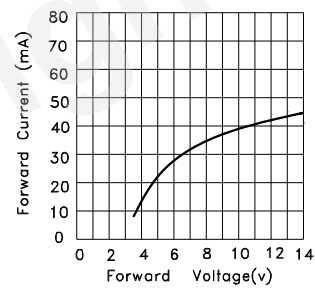
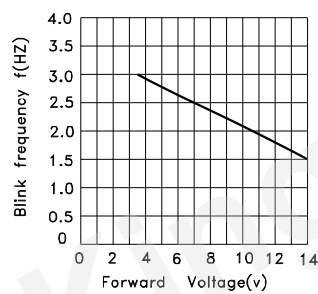
1. 2mm below package base.

2. 5mm below package base.



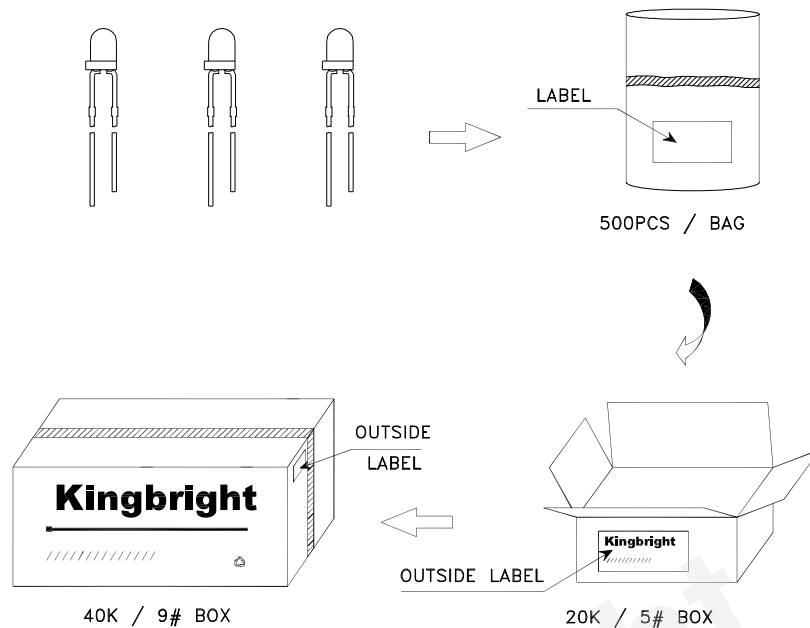
High Efficiency Red


L-36BID



PACKING & LABEL SPECIFICATIONS

L-36BID



Kingbright	
P/NO: L-36Bxxx	
QTY: 500 pcs	Q.C. Q C xx xx xxxx PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

Terms and conditions for the usage of this document

- 1.The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2.The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3.When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4.The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5.The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6.All design applications should refer to Kingbright application notes available at http://www.kingbright.com/application_notes

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



Fig.1

”○” Correct mounting method ”×” Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



Fig. 2

Fig. 3

Fig. 4

4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)



Fig. 5

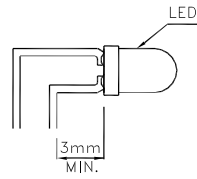


Fig. 6

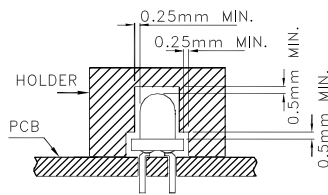


Fig. 7

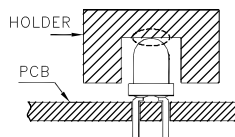


Fig. 8

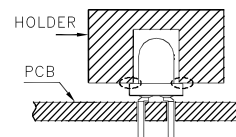
7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



○



×



×

8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profiles:



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.